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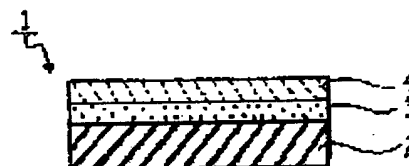
(54) WAFER STICKING ADHESIVE SHEET

(57)Abstract:

PURPOSE: To avoid the deviation in chip bodies for enabling the pick up to be stably performed by a method wherein the modulus of elasticity after radiation setting of radiation setting adhesive layer comprising a bonding agent and radiation polymeric oligomer is to be specified.

CONSTITUTION: The title wafer sticking adhesive sheet 1 is formed by forming a radiation setting adhesive layer 3 on a base substance 2 further forming a die bonding agent layer 4 on the layer 3.

The modulus of elasticity of the radiation setting adhesive layer 3 after the radiation setting step is specified to be 1×10^6 [dynes/cm²]- 1×10^8 [dynes/cm²] comprising the radiation setting adhesive layer 3, an acryl base adhesive is preferable while as for the radiation polymeric oligomer, respective oligomers, etc., of urethane acrylate base, epoxy denatured urethane acrylate base, epoxy acrylate base are applicable.



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